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OTHER DO	CUME	NTS	(1	incl	udi	ing /	Aut	hor.	Title, Date, Po	ertinent Pages. Etc.)				
ZOR	1. Gautam Meda "13.2: Support Design For Reducing The Sag Of Horizontally Supported Sheets" 2000 SID pp. 161-163													
,		2.	2. Rolf Aschenbrenner "Flip Chip Attachment Using Anisotropic Conductive Adhesives and Electroless Nickel Bumps" 1997 IEEE pp.95–100											
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\$		4. H. Nishida et al. "Micropitch Connection Using Anisotropic Conductive Materials For Driver IC Attachment To A Liquid Crystal Display" 1998 pp. 517-525												
EXAMINER 20.44 A.									DATE CONSIDERED					

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

(Form PTO-1449 [6-4])